

LTM4608A 68LD 15mm X 9mm X 2.82mm (TABLE OF MATERIAL DECLARATION)							
<i>The LTM4608A is RoHS compliant per EU RoHS Directive 2003/95/EC.</i>							
It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)							
No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.2125	Barium Compounds	7727-43-7	0.0032	1.50
				Filler Substances (Silica Crystalline)	73776-74-4	0.0848	39.91
				Copper Metal	7631-86-9	0.1190	56.00
				Copper Compounds	7440-50-8	0.0000	0.02
				Ecotoxic substances	1328-53-6	0.0000	0.00
				Gold metal or alloy	7439-92-1	0.0010	0.46
				Nickel	7440-57-5	0.0045	2.10
				Zinc	7440-02-0	0.0000	0.01
2	Solder Paste	Alloy	0.0337	Sn	7440-66-6	0.0320	95.00
				Sb	7440-31-5	0.0017	5.00
3	Epoxy	Alloy	0.0020	Di-ester resin	non-disclosure	0.0002	10.00
				Functionalized ester	non-disclosure	0.0002	10.00
				Silver	7440-22-4	0.0016	80.00
4	Passive/Active Components		0.2818	Ni Oxide	1313-99-1	0.0202	7.18
				Cu Oxide	1317-38-0	0.0068	2.42
				Zn Oxide	1314-13-2	0.0308	10.94
				Fe Oxide	1309-37-1	0.1123	39.86
				Copper (Cu)	7440-50-8	0.0655	23.23
				Nickel (Ni)	7440-02-0	0.0052	1.83
				Tin (Sn)	7440-31-5	0.0038	1.37
				Ceramic (Ba Compounds)	12047-27-7	0.0371	13.17
5	Active Ics	Silicon	0.1028	Silicon	7440-21-3	0.1028	100.00
6	Wire	Gold	0.0027	Au	7440-57-5	0.0027	100.00
7	Encapsulation	Epoxy Resin	0.7207	Fused Silica	60676-86-0	0.5564	77.20
				Epoxy Resin	-	0.0641	8.90
				Phenol Resin	-	0.0641	8.90
				Crytalline Silica	14808-60-7	0.0216	3.00
				Carbon Black	1333-86-4	0.0036	0.50
				Metal Hydroxide	-	0.0108	1.50
Total Package Weight			1.3562				

Note: Composition derived from MSDS and material C of C from Vendors
Component Weight based on assembly of generic parts